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4 Revision History

DATE	REVISION	NOTES
August 2023	*	Initial Release

5 Pin Configuration and Functions

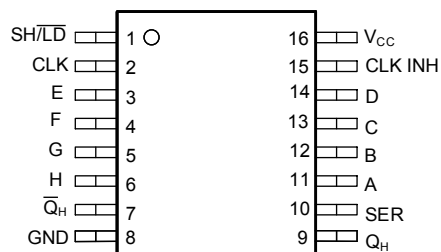


Figure 5-1. SN74HC165B-EP: PW Package, 16-Pin TSSOP (Top View)

Table 5-1. Pin Functions

PIN		TYPE ⁽¹⁾	DESCRIPTION
NAME	NO.		
A	11	I	Serial input A
B	12	I	Serial input B
C	13	I	Serial input C
CLK	2	I	Storage clock
CLK INH	15	I	Storage clock
D	14	I	Serial input D
E	3	I	Serial input E
F	4	I	Serial input F
G	5	I	Serial input G
GND	8	—	Ground pin
H	6	I	Serial input H
$\overline{Q}_H$	7	O	Output H, inverted
Q_H	9	O	Output H
SH/ $\overline{LD}$	1	I	Load Input
SER	10	I	Serial input
V_{CC}	16	—	Power pin

(1) I = Input, O = Output, I/O = Input or Output, G = Ground, P = Power.

6 Specifications

6.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted)⁽¹⁾

			MIN	MAX	UNIT
V _{CC}	Supply voltage		–0.5	7	V
V _I	Input voltage ⁽²⁾		–0.5	7	V
V _O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾		–0.5	7	V
V _O	Output voltage ⁽²⁾ ⁽³⁾		–0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V _I < 0		±20	mA
I _{OK}	Output clamp current	V _O < 0		±20	mA
I _O	Continuous output current	V _O = 0 to V _{CC}		±25	mA
	Continuous current through V _{CC} or GND			±50	mA
T _{stg}	Storage temperature		–65	150	°C

- (1) Operation outside the *Absolute Maximum Ratings* may cause permanent device damage. *Absolute Maximum Ratings* do not imply functional operation of the device at these or any other conditions beyond those listed under *Recommended Operating Conditions*. If used outside the *Recommended Operating Conditions* but within the *Absolute Maximum Ratings*, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) This value is limited to 5.5 V maximum.

6.2 ESD Ratings

			VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2000	V
		Charged-device model (CDM), per ANSI/ESDA/JEDEC JS-002 ⁽²⁾	±1000	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

			MIN	MAX	UNIT
V _{CC}	Supply voltage		2	6	V
V _{IH}	High-level input voltage	V _{CC} = 2 V	1.5		V
		V _{CC} = 4.5 V	3.15		
		V _{CC} = 6 V	4.2		
V _{IL}	Low-level input voltage	V _{CC} = 2 V		0.5	V
		V _{CC} = 4.5 V		1.35	
		V _{CC} = 6 V		1.8	
V _I	Input voltage		0	V _{CC}	V
V _O	Output voltage		0	V _{CC}	V
Δt/Δv	Input transition rise or fall rate	V _{CC} = 2 V		1000	ns/V
		V _{CC} = 4.5 V		500	
		V _{CC} = 6 V		400	
T _A	Operating free-air temperature		–55	125	°C

(1) All unused inputs of the device must be held at V_{CC} or GND for proper device operation. See [Implications of Slow or Floating CMOS Inputs](#).

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		SN74HC165B-EP	UNIT
		PW (TSSOP)	
		16 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	131.2	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	69.4	°C/W
R _{θJB}	Junction-to-board thermal resistance	75.8	°C/W
Ψ _{JT}	Junction-to-top characterization parameter	21.0	°C/W
Ψ _{JB}	Junction-to-board characterization parameter	75.4	°C/W
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	—	°C/W

(1) For more information about traditional and new thermal metrics, see [Semiconductor and IC Package Thermal Metrics](#).

6.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted).

PARAMETER		V _{CC}	MIN	TYP	MAX	UNIT
V _{OH}	I _{OH} = −20 μA	2 V to 6 V	V _{CC} − 0.1			V
	I _{OH} = −4 mA	4.5 V	3.7	4.3		
	I _{OH} = −5.2 mA	6 V	5.2	5.8		
V _{OL}	I _{OL} = 20 μA	2 V to 6 V			0.1	V
	I _{OL} = 4 mA	4.5 V		0.17	0.4	
	I _{OL} = 5.2 mA	6 V		0.15	0.4	
I _I	V _I = V _{CC} or GND	6 V		±0.1	±1	μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	6 V			160	μA
C _i	V _I = V _{CC} or GND	2 V to 6 V		3	10	pF

6.6 Timing Requirements, V_{CC} = 2 V

over recommended operating free-air temperature range (unless otherwise noted) (see [Section 7](#))

PARAMETER	TEST CONDITION	25°C		–55°C to 125°C		UNIT
		MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency	6		4.2		MHz
t _w	CLK high or low	80		120		ns
	SH/ $\overline{\text{LD}}$ low	80		120		
t _{su}	SH/ $\overline{\text{LD}}$ high before CLK↑	80		120		ns
	SER before CLK↑	40		60		
	CLK INH before CLK↑	100		150		
	Data before SH/ $\overline{\text{LD}}$ ↑	100		150		
t _h	SER data after CLK↑	5		5		ns
	Parallel data after SH/ $\overline{\text{LD}}$ ↑	5		5		
	SH/ $\overline{\text{LD}}$ high after CLK↑	5		5		

6.7 Timing Requirements, V_{CC} = 4.5 V

over recommended operating free-air temperature range (unless otherwise noted) (see [Section 7](#))

PARAMETER	TEST CONDITION	25°C		–55°C to 125°C		UNIT
		MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency	31		21		MHz
t _w	CLK high or low	16		24		ns
	SH/ $\overline{\text{LD}}$ low	16		24		
t _{su}	SH/ $\overline{\text{LD}}$ high before CLK↑	16		24		ns
	SER before CLK↑	8		12		
	CLK INH before CLK↑	20		30		
	Data before SH/ $\overline{\text{LD}}$ ↑	20		30		
t _h	SER data after CLK↑	5		5		ns
	Parallel data after SH/ $\overline{\text{LD}}$ ↑	5		5		
	SH/ $\overline{\text{LD}}$ high after CLK↑	5		5		

6.8 Timing Requirements, $V_{CC} = 6\text{ V}$

over recommended operating free-air temperature range (unless otherwise noted) (see [Section 7](#))

PARAMETER	TEST CONDITION	25°C		–55°C to 125°C		UNIT
		MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		36		25	MHz
t_w	Pulse duration					ns
	CLK high or low	14		20		
t_{su}	SH/ $\overline{\text{LD}}$ low	14		20		ns
	SH/ $\overline{\text{LD}}$ high before CLK $\uparrow$	14		20		
	SER before CLK $\uparrow$	7		10		
	CLK INH before CLK $\uparrow$	17		25		
	Data before SH/ $\overline{\text{LD}}$ $\uparrow$	17		26		
t_h	Hold time					ns
	SER data after CLK $\uparrow$	5		5		
	Parallel data after SH/ $\overline{\text{LD}}$ $\uparrow$	5		5		
	SH/ $\overline{\text{LD}}$ high after CLK $\uparrow$	5		5		

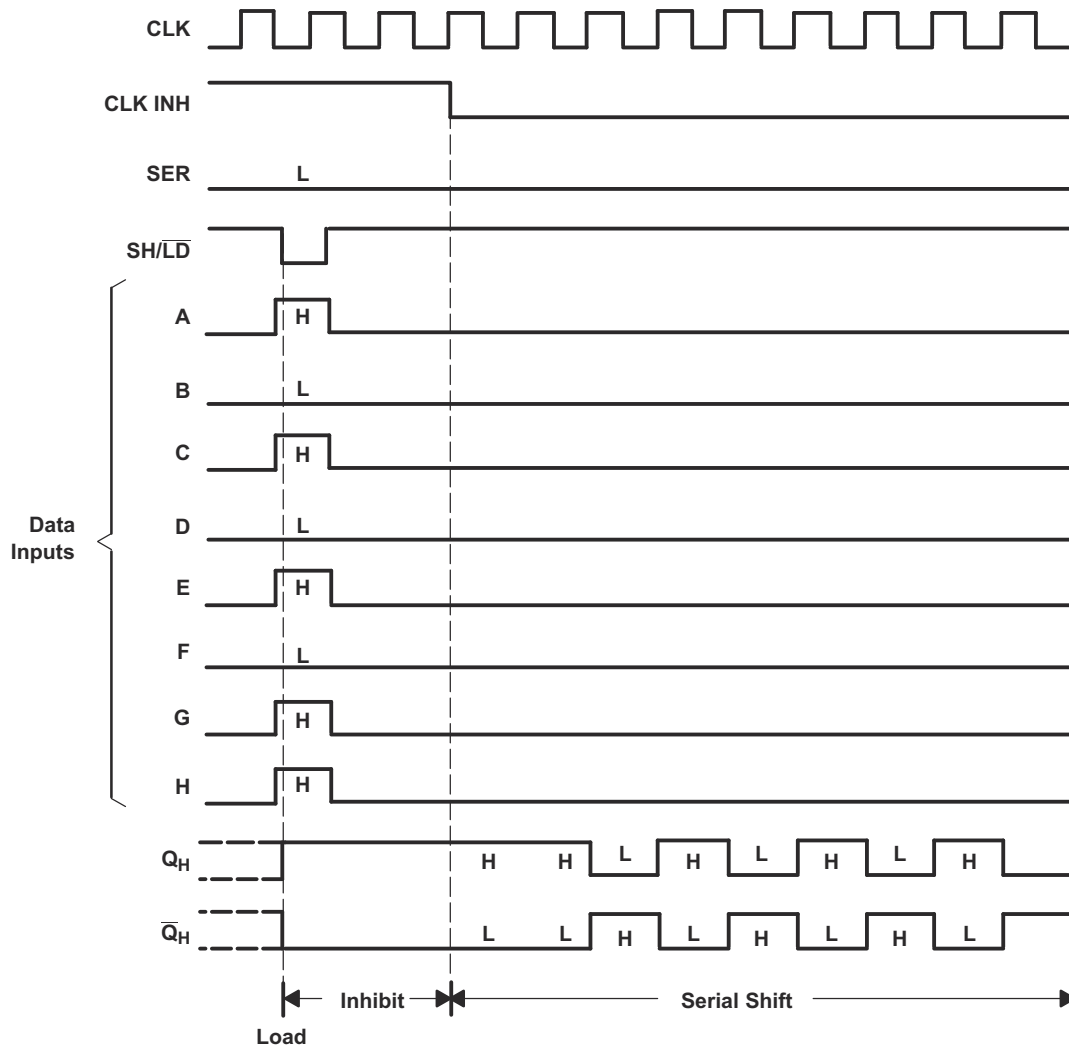


Figure 6-1. Typical Shift, Load, and Inhibit Sequences

6.9 Switching Characteristics, $V_{CC} = 2\text{ V}$

over operating free-air temperature range (unless otherwise noted), (see [Section 7](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAP	25°C			–55°C to 125°C			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
t_{pd}	CLK	Q_H or $\overline{Q}$	$C_L = 50\text{ pF}$		75	150			225	ns
	SH/ $\overline{LD}$				80	150			225	
	H				75	150			225	

6.10 Switching Characteristics, $V_{CC} = 4.5\text{ V}$

over operating free-air temperature range (unless otherwise noted), (see [Section 7](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAP	25°C			–55°C to 125°C			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
t_{pd}	CLK	Q_H or $\overline{Q}$	$C_L = 50\text{ pF}$		15	30			45	ns
	SH/ $\overline{LD}$				20	30			45	
	H				15	30			45	

6.11 Switching Characteristics, $V_{CC} = 6\text{ V}$

over recommended operating free-air temperature range (unless otherwise noted), (see [Section 7](#))

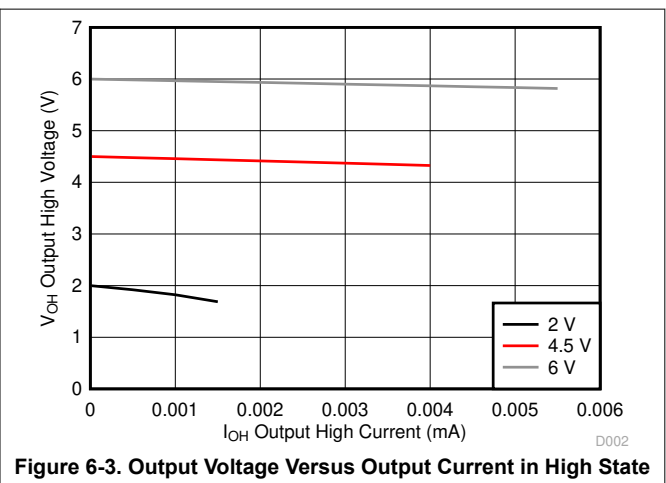
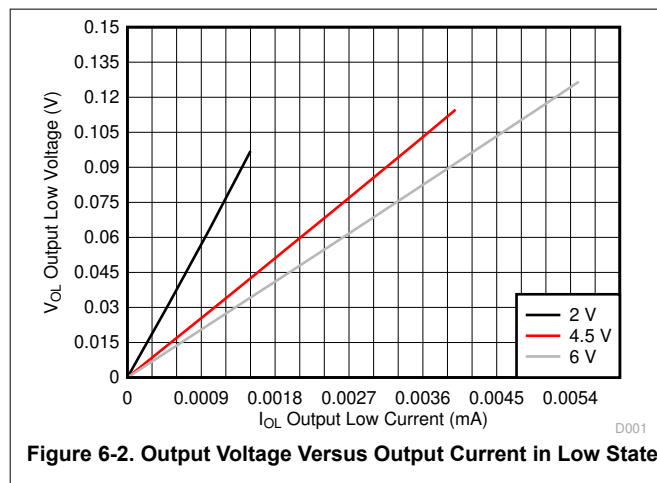
PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAP	25°C			–55°C to 125°C			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
t_{pd}	CLK	Q_H or $\overline{Q}$	$C_L = 50\text{ pF}$		13	26			38	ns
	SH/ $\overline{LD}$				16	26			38	
	H				13	26			38	

6.12 Operating Characteristics

$T_A = 25^\circ\text{C}$

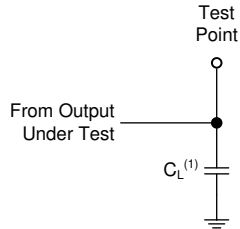
PARAMETER		TEST CONDITIONS	V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance	No load	6 V	75	pF

6.13 Typical Characteristics



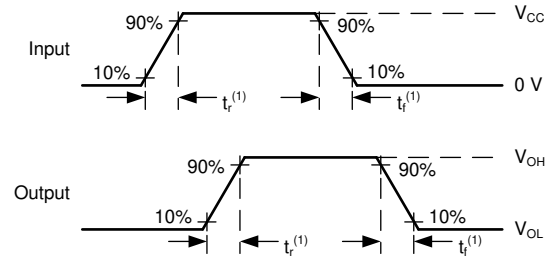
7 Parameter Measurement Information

- Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_t < 6 \text{ ns}$.
- The outputs are measured one at a time, with one input transition per measurement.



A. $C_L = 50 \text{ pF}$ and includes probe and jig capacitance.

Figure 7-1. Load Circuit



A. The maximum between t_r and t_f is used for t_t .

Figure 7-2. Voltage Waveforms Transition Times

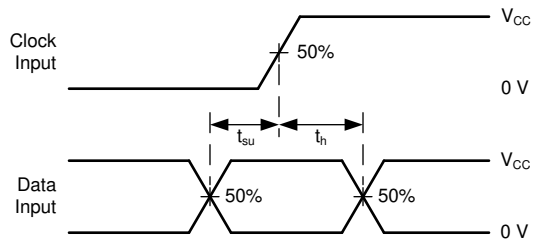


Figure 7-3. Voltage Waveforms Setup and Hold Times

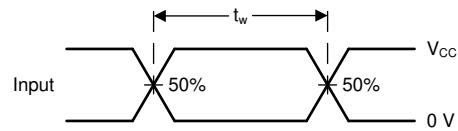
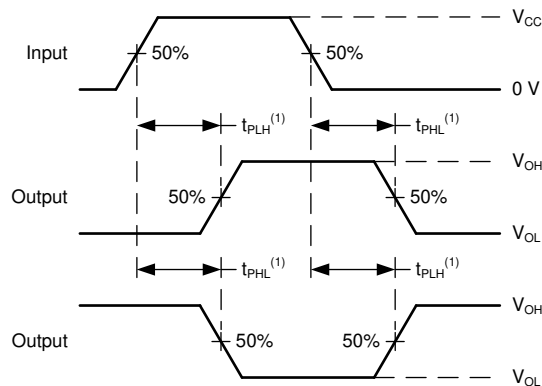


Figure 7-4. Voltage Waveforms Pulse Width



A. The maximum between t_{pLH} and t_{PHL} is used for t_{pd} .

Figure 7-5. Voltage Waveforms Propagation Delays

8.3.3 Clamp Diode Structure

Figure 8-1 shows the inputs and outputs to this device have negative clamping diodes only.

CAUTION

Voltages beyond the values specified in the *Absolute Maximum Ratings* table can cause damage to the device. The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

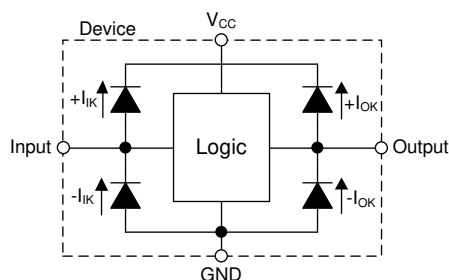


Figure 8-1. Electrical Placement of Clamping Diodes for Each Input and Output

8.4 Device Functional Modes

Table 8-1 and Table 8-2 list the functional modes of the SN74HC165B-EP.

Table 8-1. Operating Mode Table

INPUTS ⁽¹⁾			FUNCTION
SH/LD	CLK	CLK INH	
L	X	X	Parallel load
H	H	X	No change
H	X	H	No change
H	L	↑	Shift ⁽²⁾
H	↑	L	Shift ⁽²⁾

(1) H = High Voltage Level, L = Low Voltage Level, X = Do Not Care, ↑ = Low to High transition

(2) Shift: content of each internal register shifts towards serial output Q_H. Data at SER is shifted into the first register.

Table 8-2. Output Function Table

INTERNAL REGISTERS ^{(1) (2)}		OUTPUTS ⁽²⁾	
A — G	H	Q	Q̄
X	L	L	H
X	H	H	L

(1) Internal registers refer to the shift registers inside the device. These values are set by either loading data from the parallel inputs, or by clocking data in from the serial input.

(2) H = High Voltage Level, L = Low Voltage Level, X = Do Not Care

9 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

9.1 Application Information

The SN74HC165B-EP is a low drive CMOS device that can be used for a multitude of bus interface type applications where output ringing is a concern. The low-drive and slow-edge rates minimize overshoot and undershoot on the outputs.

9.2 Typical Application

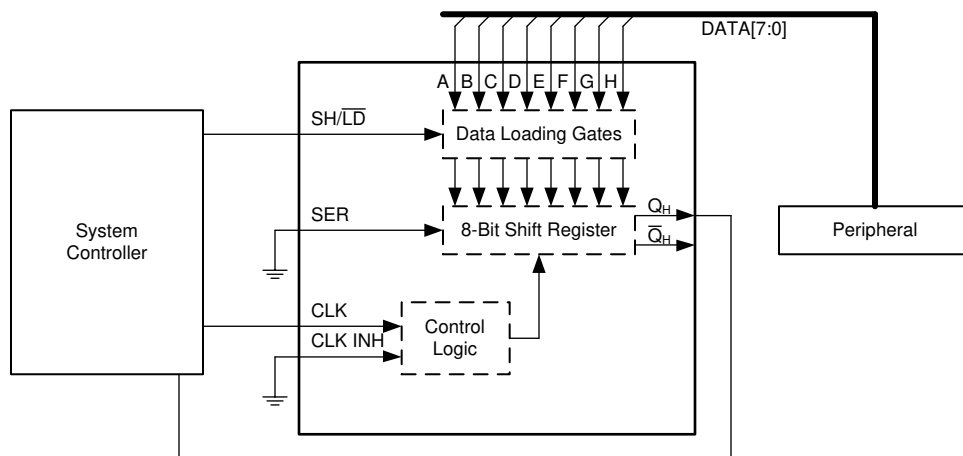


Figure 9-1. Input Expansion with Shift Registers

9.2.1 Power Considerations

Ensure the desired supply voltage is within the range specified in the *Recommended Operating Conditions*. The supply voltage sets the device's electrical characteristics as described in the *Electrical Characteristics* section.

The positive voltage supply must be capable of sourcing current equal to the total current to be sourced by all outputs of the SN74HC165B-EP plus the maximum static supply current, I_{CC} , listed in the *Electrical Characteristics*, and any transient current required for switching. The logic device can only source as much current that is provided by the positive supply source. Be sure to not exceed the maximum total current through V_{CC} listed in the *Absolute Maximum Ratings*.

The ground must be capable of sinking current equal to the total current to be sunk by all outputs of the SN74HC165B-EP plus the maximum supply current, I_{CC} , listed in the *Electrical Characteristics*, and any transient current required for switching. The logic device can only sink as much current that can be sunk into its ground connection. Be sure to not exceed the maximum total current through GND listed in the *Absolute Maximum Ratings*.

The SN74HC165B-EP can drive a load with a total capacitance less than or equal to 50 pF while still meeting all of the data sheet specifications. Larger capacitive loads can be applied; however, it is not recommended to exceed 50 pF.

The SN74HC165B-EP can drive a load with total resistance described by $R_L \geq V_O / I_O$, with the output voltage and current defined in the *Electrical Characteristics* table with V_{OH} and V_{OL} . When outputting in the HIGH state, the output voltage in the equation is defined as the difference between the measured output voltage and the supply voltage at the V_{CC} pin.

Total power consumption can be calculated using the information provided in [CMOS Power Consumption and Cpd Calculation](#).

Thermal increase can be calculated using the information provided in [Thermal Characteristics of Standard Linear and Logic \(SLL\) Packages and Devices](#).

CAUTION

The maximum junction temperature, $T_{J(max)}$ listed in the *Absolute Maximum Ratings*, is an additional limitation to prevent damage to the device. Do not violate any values listed in the *Absolute Maximum Ratings*. These limits are provided to prevent damage to the device.

9.2.2 Input Considerations

Input signals must cross $V_{IL(max)}$ to be considered a logic LOW, and $V_{IH(min)}$ to be considered a logic HIGH. Do not exceed the maximum input voltage range found in the *Absolute Maximum Ratings*.

Unused inputs must be terminated to either V_{CC} or ground. The unused inputs can be directly terminated if the input is completely unused, or they can be connected with a pull-up or pull-down resistor if the input will be used sometimes, but not always. A pull-up resistor is used for a default state of HIGH, and a pull-down resistor is used for a default state of LOW. The drive current of the controller, leakage current into the SN74HC165B-EP (as specified in the *Electrical Characteristics*), and the desired input transition rate limits the resistor size. A 10-k Ω resistor value is often used due to these factors.

The SN74HC165B-EP has CMOS inputs and thus requires fast input transitions to operate correctly, as defined in the *Recommended Operating Conditions* table. Slow input transitions can cause oscillations, additional power consumption, and reduction in device reliability.

Refer to the *Feature Description* section for additional information regarding the inputs for this device.

9.2.3 Output Considerations

The positive supply voltage is used to produce the output HIGH voltage. Drawing current from the output will decrease the output voltage as specified by the V_{OH} specification in the *Electrical Characteristics*. The ground voltage is used to produce the output LOW voltage. Sinking current into the output will increase the output voltage as specified by the V_{OL} specification in the *Electrical Characteristics*.

Push-pull outputs that could be in opposite states, even for a very short time period, should never be connected directly together. This can cause excessive current and damage to the device.

Two channels within the same device with the same input signals can be connected in parallel for additional output drive strength.

Unused outputs can be left floating. Do not connect outputs directly to V_{CC} or ground.

Refer to the *Feature Description* section for additional information regarding the outputs for this device.

9.2.4 Detailed Design Procedure

1. Add a decoupling capacitor from V_{CC} to GND. The capacitor needs to be placed physically close to the device and electrically close to both the V_{CC} and GND pins. An example layout is shown in the *Layout* section.
2. Ensure the capacitive load at the output is ≤ 50 pF. This is not a hard limit; by design, however, it will optimize performance. This can be accomplished by providing short, appropriately sized traces from the SN74HC165B-EP to one or more of the receiving devices.
3. Ensure the resistive load at the output is larger than $(V_{CC} / I_{O(max)}) \Omega$, which will not violate the maximum output current from the *Absolute Maximum Ratings*. Most CMOS inputs have a resistive load measured in $M\Omega$; much larger than the minimum calculated previously.
4. Thermal issues are rarely a concern for logic gates; the power consumption and thermal increase, however, can be calculated using the steps provided in the application report, [CMOS Power Consumption and Cpd Calculation](#).

9.2.5 Application Curves

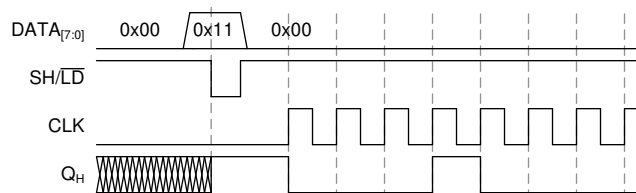


Figure 9-2. Application Timing Diagram

9.3 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Absolute Maximum Ratings* section. Each V_{CC} terminal must have a good bypass capacitor to prevent power disturbance. For devices with a single supply, TI recommends a 0.1- μ F capacitor; if there are multiple V_{CC} terminals, then TI recommends a 0.01- μ F or 0.022- μ F capacitor for each power terminal. Multiple bypass capacitors can be paralleled to reject different frequencies of noise. Frequencies of 0.1 μ F and 1 μ F are commonly used in parallel. The bypass capacitor must be installed as close as possible to the power terminal for best results.

9.4 Layout

9.4.1 Layout Guidelines

When using multiple bit logic devices, inputs should not float. In many cases, functions or parts of functions of digital logic devices are unused. Some examples are when only two inputs of a triple-input AND gate are used, or when only 3 of the 4-buffer gates are used. Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or V_{CC} , whichever makes more sense for the logic function or is more convenient.

9.4.2 Layout Example

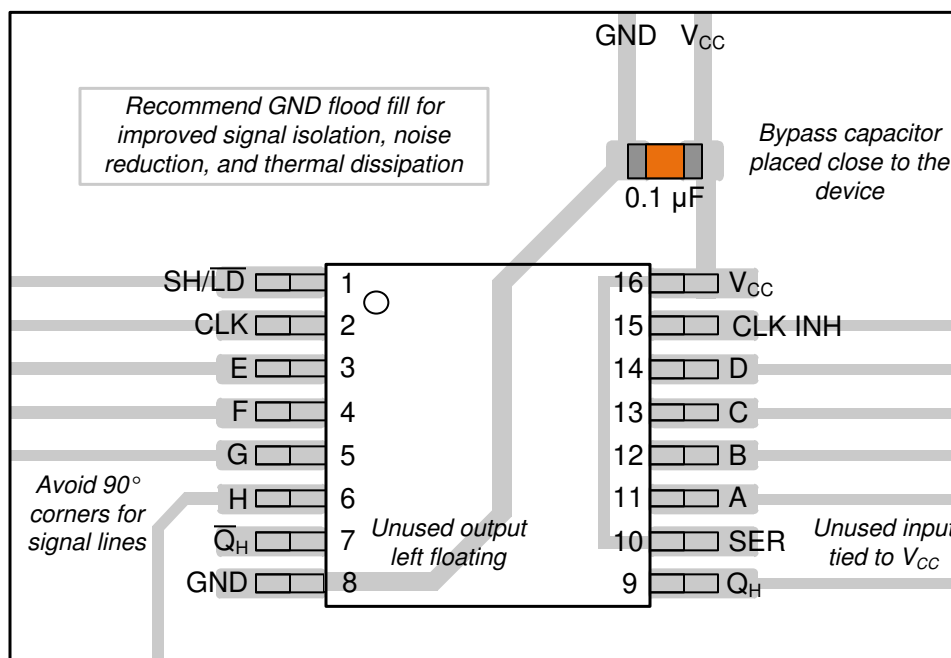


Figure 9-3. Layout Example for the SN74HC165B-EP in the PW Package

10 Device and Documentation Support

10.1 Related Documentation

For related documentation, see the following:

- Texas Instruments, [Power-Up Behavior of Clocked Devices](#)
- Texas Instruments, [Introduction to Logic](#)

10.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates—including silicon errata—go to the product folder for your device on [ti.com](https://www.ti.com). In the upper right-hand corner, click the *Alert me* button. This registers you to receive a weekly digest of product information that has changed (if any). For change details, check the revision history of any revised document.

10.3 Support Resources

TI E2E™ [support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

10.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

All trademarks are the property of their respective owners.

10.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

10.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74HC165BMPWREP	Active	Production	TSSOP (PW) 16	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC165EP
SN74HC165BMPWREP.A	Active	Production	TSSOP (PW) 16	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC165EP
V62/23621-01XE	Active	Production	TSSOP (PW) 16	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	See SN74HC165BMPWREP	HC165EP

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

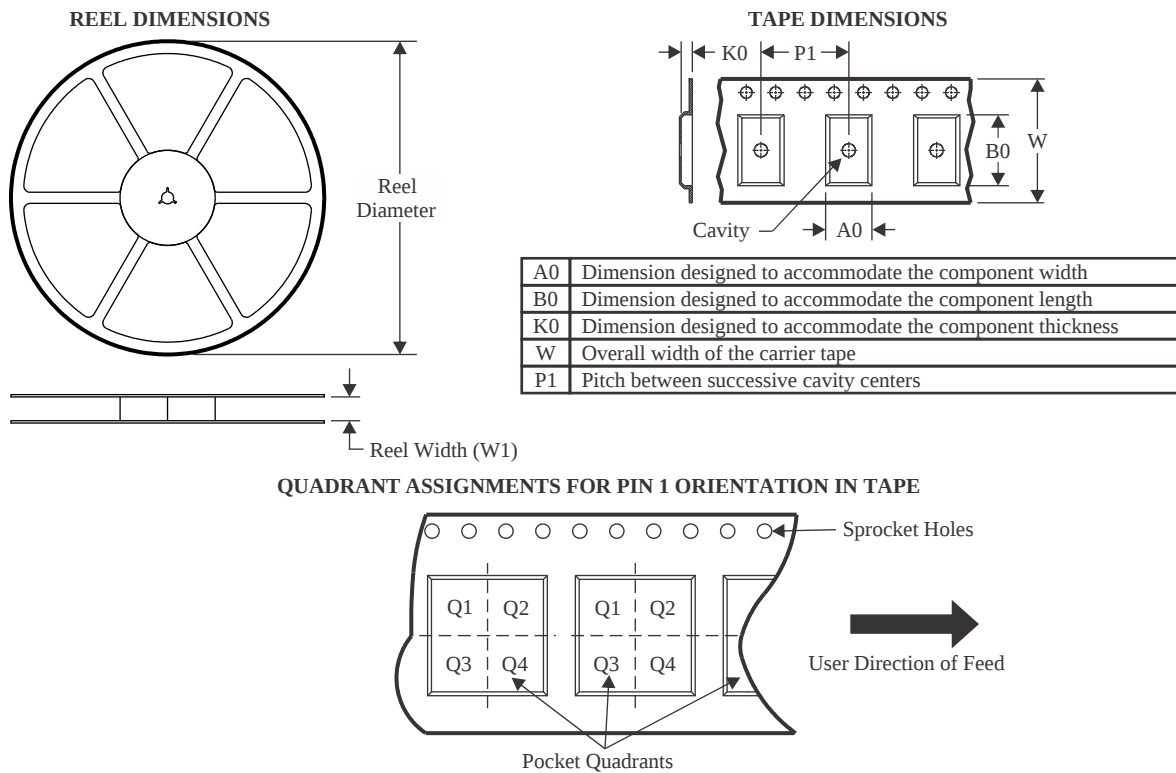
⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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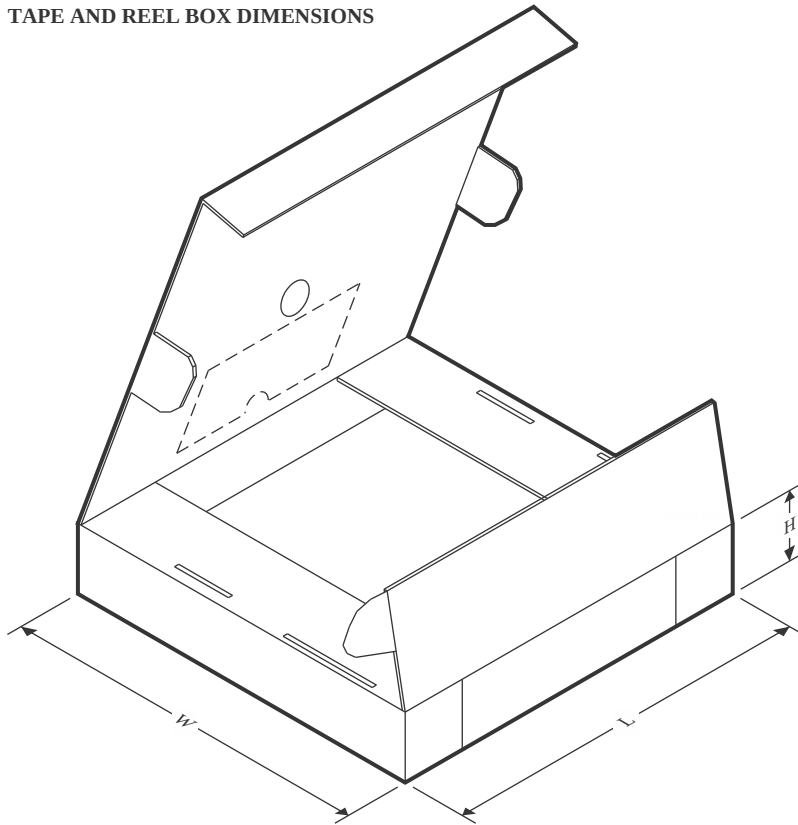
TAPE AND REEL INFORMATION



*All dimensions are nominal

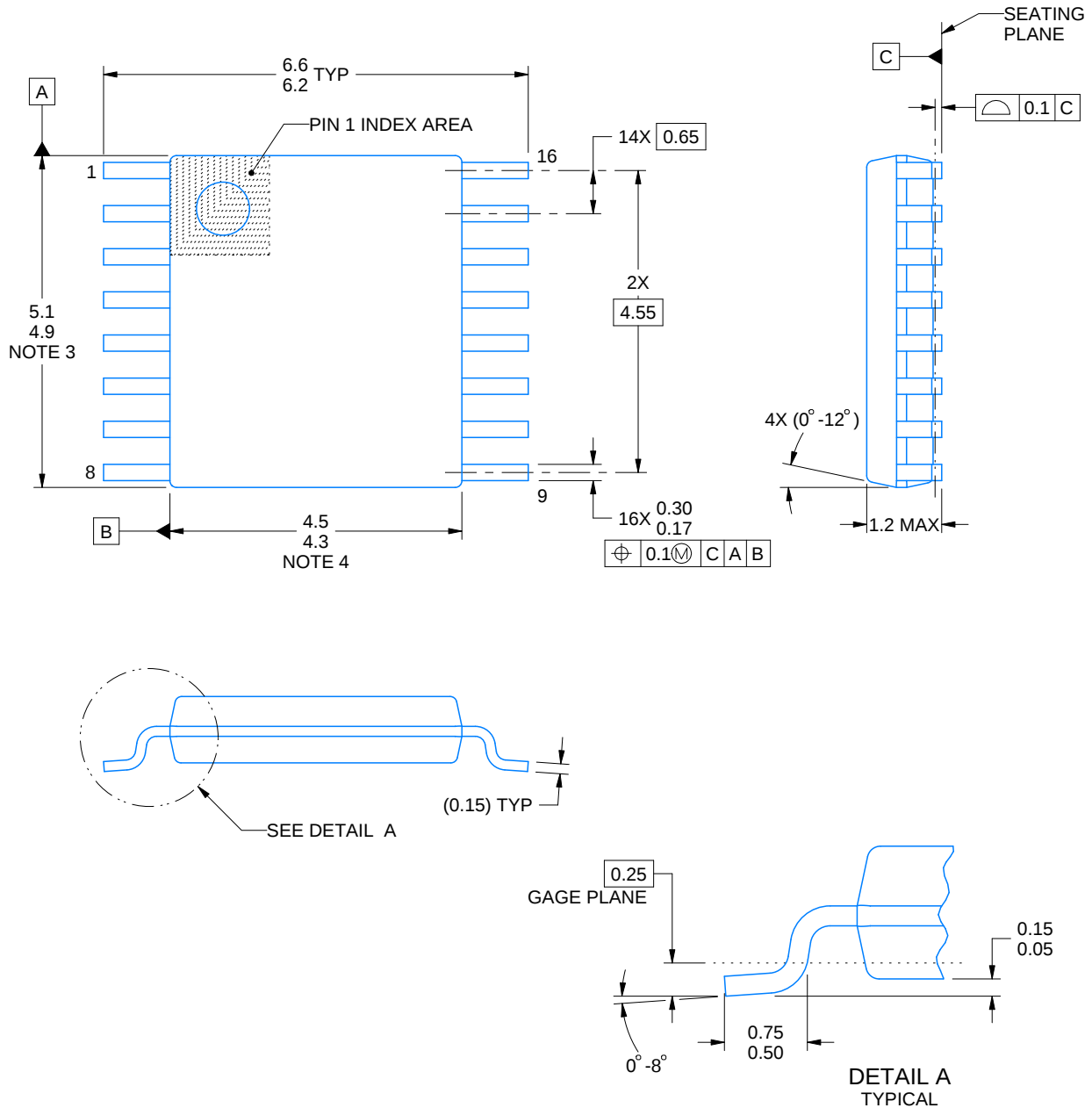
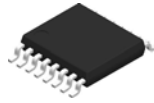
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC165BMPWREP	TSSOP	PW	16	3000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC165BMPWREP	TSSOP	PW	16	3000	353.0	353.0	32.0



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NOTES:

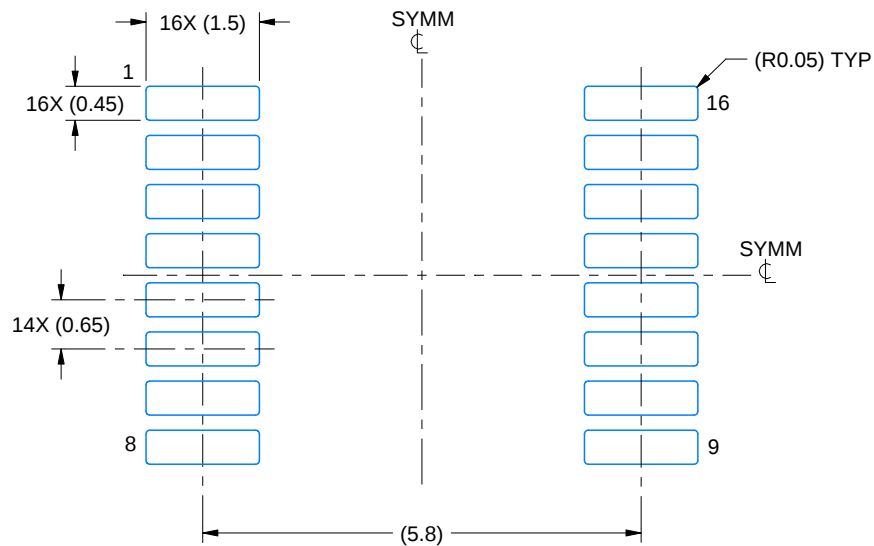
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

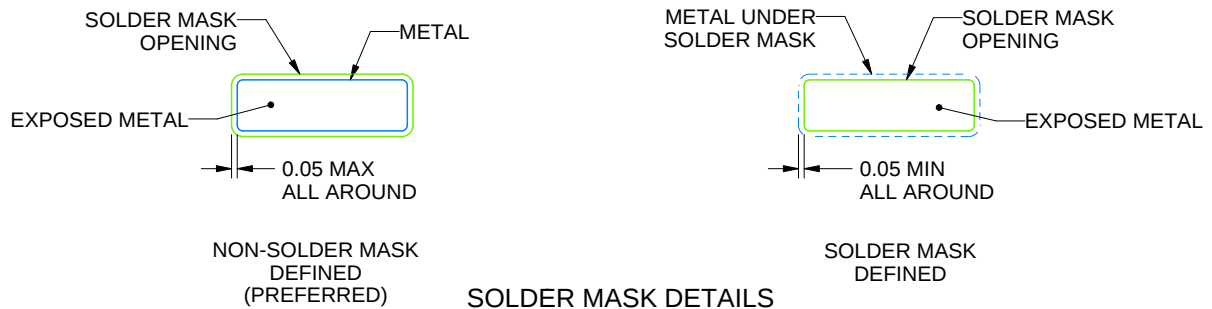
PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



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NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

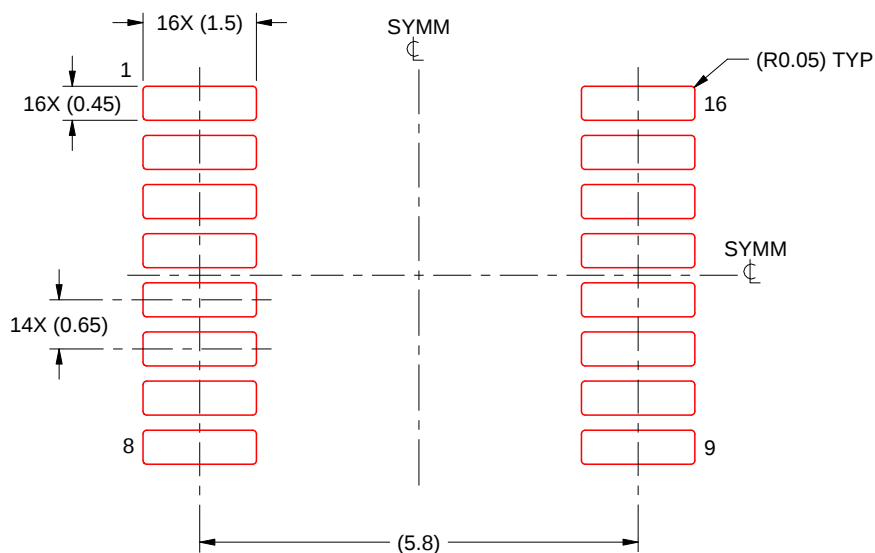
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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Last updated 10/2025